

RoHS

COMPLIANT HALOGEN

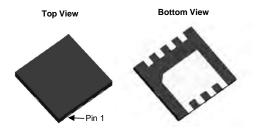
FREE

Available

N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
100	0.036 at V_{GS} = 10 V	21	23 nC		
100	0.0375 at V _{GS} = 8 V	17	23110		

DFN 3x3 EP

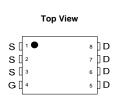


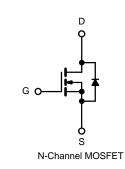
FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- Extremely Low Q_{gd} for Switching Losses
- 100 % Rg Tested
- 100 % Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• Primary Side Switch





Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	100	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		21		
Continuous Droin Current (T 150 °C)	T _C = 70 °C		17		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _A = 25 °C	I _D	15 ^{b, c}		
	T _A = 70 °C	-	13 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	50	A	
Continuous Source-Drain Diode Current	T _C = 25 °C		4.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	۱ _S	2.6 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20		
Single Pulse Avalanche Energy		E _{AS}	20	mJ	
	T _C = 25 °C		5.9		
Movimum Dower Dissinction	T _C = 70 °C		3.8	w	
Maximum Power Dissipation	T _A = 25 °C	PD	3.1 ^{b, c}	vv	
	T _A = 70 °C	1	2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, †}	t ≤ 10 s	R _{thJA}	33	40	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	17	21	- C/W	

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under steady state conditions is 80 °C/W.

VBQF1104N

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V	
V _{DS} Temperature Coefficient				172			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 10		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2.5		4.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I _{DSS} –	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current		$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30			A	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		0.036			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 8 \text{ V}, I_{D} = 5 \text{ A}$		0.0375		Ω	
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 5 A		23		S	
Dynamic ^b	-10				1		
Input Capacitance	C _{iss}			1735			
Output Capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		160		pF	
Reverse Transfer Capacitance	C _{rss}			37			
Total Gate Charge	Q _g –	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		28.5	43	nC	
				23	35		
Gate-Source Charge	Q _{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 5 \text{ A}$		8			
Gate-Drain Charge	Q _{gd}	20 00 2		6.5			
Gate Resistance	R _q	f = 1 MHz		0.85	1.3	Ω	
Turn-on Delay Time	t _{d(on)}			14	21		
Rise Time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_{\text{I}} = 10 \Omega$		12	18	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{GEN} = 10 \text{ V}, \text{R}_g = 1 \Omega$		22	33		
Fall Time	t _f	-		6	10	1	
Turn-On Delay Time	t _{d(on)}			16	24	ns	
Rise Time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_{\text{I}} = 10 \Omega$		12	18	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5 \text{ A}, V_{\text{GEN}} = 8 \text{ V}, R_q = 1 \Omega$		20	30		
Fall Time	t _f	0		7	12	-	
Drain-Source Body Diode Characteristic				<u> </u>		<u> </u>	
Continuous Source-Drain Diode Current	۱ _s	T _C = 25 °C			7.7		
Pulse Diode Forward Current ^a	I _{SM}	-			50	A	
Body Diode Voltage	V _{SD}	I _S = 2.6 A		0.77	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	-		63	95	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			110	165	nC	
Reverse Recovery Fall Time	t _a	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		49			
Reverse Recovery Rise Time	t _b			14		ns	

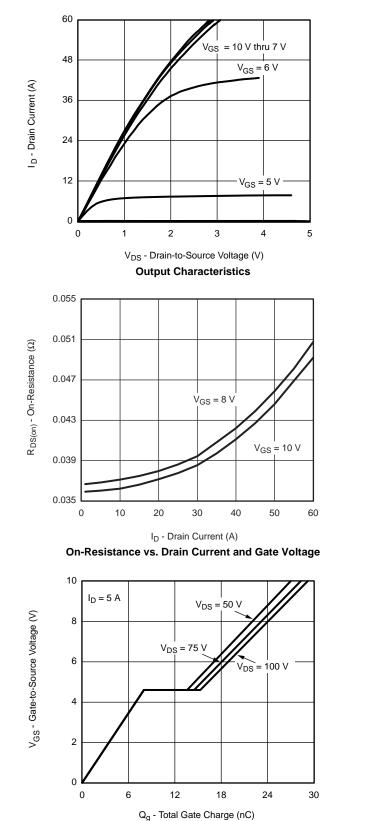
Notes:

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$

a. Guaranteed by design, not subject to production testing.

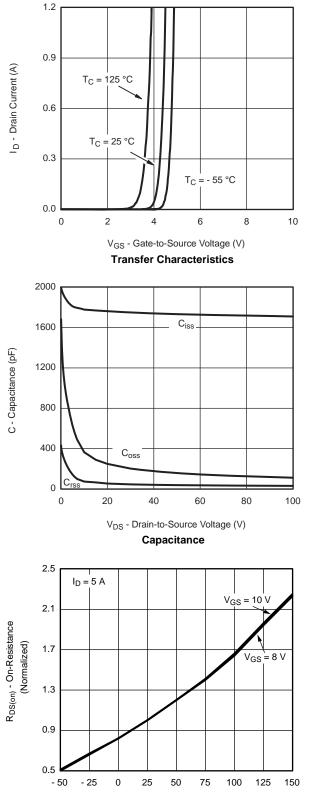
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





Gate Charge

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

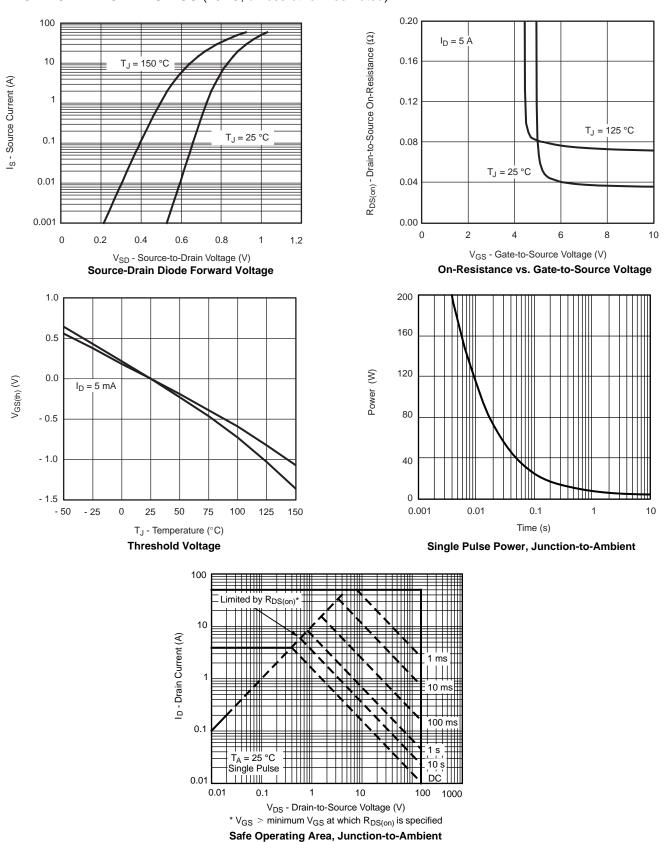


T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

服务热线:400-655-8788

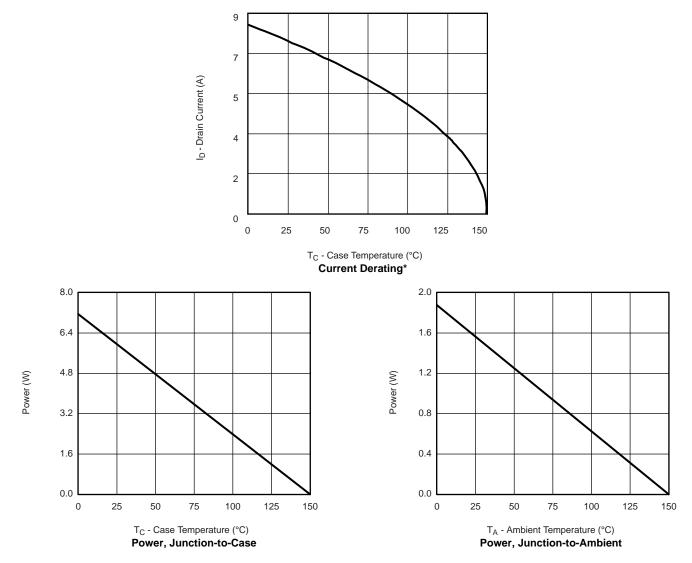




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



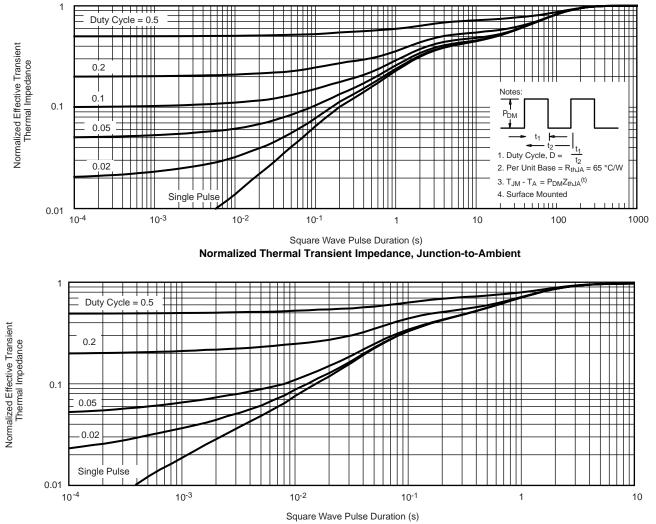
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

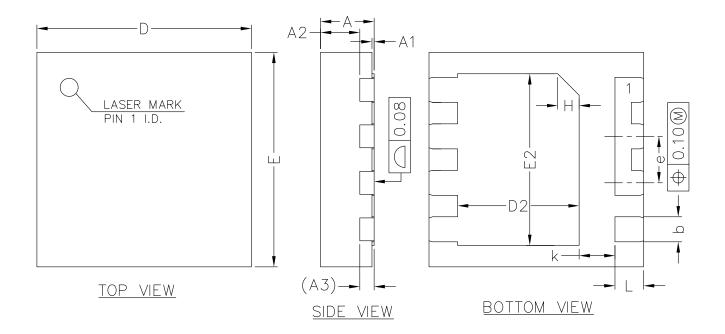


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot







<u>SIDE VIEW</u>

SYMBOL	MIN	NOM	MAX			
А	0.70	0.75	0.80			
A1	0.00	0.02	0.05			
A2	0.50	0.55	0.60			
A3	0.20REF					
b	0.30	0.35	0.40			
D	2.90	3.00	3.10			
E	2.90	3.00	3.10			
D2	1.60	1.70	1.80			
E2	2.30	2.40	2.50			
е	0.55	0.65	0.75			
К	0.40	0.50	0.60			
L	0.35	0.40	0.45			

COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)



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